Attendance:

Mr. Jesse JaramilloAmphenolMr. Greg McSorleyAmphenolMr. Jaremy FlakeATL TechnologyMr. Kevin WittDallas SemiconductorMr. Mickey FeltonEMCMr. Elwood ParsonsFoxconn ElectronicsMr. Mike FitzpatrickFujitsuMr. Barry OlawskyHewlett Packard Co.Mr. James RockrohrIBM Corp.Mr. Harvey NewmanInfineon TechnologiesDr. Mark SeidelIntel Corp.Mr. Gabriel RomeroLSI Logic Corp.Mr. Galen FrommMolex Inc.Mr. Hock SeowNEC Electronics America, IncMr. Rick HernandezPMC-SierraMr. Joseph ChenSamsungMr. Alvin CoxSeagate TechnologyMr. Bent Hessen-SchmidtSynthesys Research, Inc.Mr. Dan GorencTycoElectronicsMr. Dan GorencTycoElectronicsMr. Dan GorencTycoElectronicsMr. Alvin CoxSeagate TechnologyMr. Bent Hessen-SchmidtSynthesys Research, Inc.Mr. Dan GorencTycoElectronicsMr. Scott ShueyTycoElectronicsMr. Ramya DissanayakeWDC	Mr. Bryan Kantack Mr. Paul von Stamwitz	Agilent Technologies, Inc. AMCC
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Mr. Bent Hessen-SchmidtSynthesys Research, Inc.Mr. Doug LoreeToshibaMr. Dan GorencTycoElectronicsMr. Scott ShueyTycoElectronicsMr. Larry McMillanWDC	Mr. Alvin Cox	Seagate Technology
Mr. Doug LoreeToshibaMr. Dan GorencTycoElectronicsMr. Scott ShueyTycoElectronicsMr. Larry McMillanWDC	Mr. Benoit Mercier	STMicroelectonics
Mr. Dan GorencTycoElectronicsMr. Scott ShueyTycoElectronicsMr. Larry McMillanWDC	Mr. Bent Hessen-Schmidt	Synthesys Research, Inc.
Mr. Scott ShueyTycoElectronicsMr. Larry McMillanWDC	Mr. Doug Loree	Toshiba
Mr. Larry McMillan WDC	Mr. Dan Gorenc	
	Mr. Scott Shuey	TycoElectronics
Mr. Ramya Dissanayake WDC		WDC
	Mr. Ramya Dissanayake	WDC

30 in attendance

Agenda:

1. StatEye (and other) simulation updates.

StatEye 5 has development site up and running, code available. Not tied directly to SAS environment yet (10 meter cable channel not run on the simulation) but debugged and should be ready for presentation on next week's conference call.

2. 07-304 SAS-2 Zero-length test load [Olawsky]

http://www.t10.org/ftp/t10/document.07/07-304r2.pdf

Measurements indicate that equivalent time scope has more accurate results (less insertion loss) than real time scopes. The effects of instrumentation are mentioned in the text, however, the measurements show it to be more than anticipated. No BERT testing available. Agilent to check on providing information regarding real time and equivalent time scope measurements.

3. New items

This is a list of concerns that need to be looked at. Please review and provide feedback.

a) Jitter tolerance test clarification?

b) Are passive interconnect specifications acceptable for 6G?

c) Test procedures for all numbers? When draft is complete, what is missing?

d) Looking at table 59 in SAS2r11 we have a specification for imbalance of 10%. From note "e", as long as the calculated rms amplitude is of the + and - legs differ by +/-5% of the midpoint it meets the spec. However, the legs could have virtually unlimited imbalance and still have the same rms amplitude. Is this a correct interpretation?

e) Do we need frequency rate of change control for SSC to avoid abrupt frequency shifts in the SSC profile?

f) What are other deficiencies in the specification?

g) Should note 17 remain?

4. 07-339r0 SAS-2 6 Gbps PHY specification [Cox] http://www.t10.org/ftp/t10/document.07/07-339r0.pdf
This is the continuation of 07-063. Includes text from SAS-2r10 as the basis for the SAS-2 PHY spec. Currently up to the 6G transmitter device section. Look at changes up to this point, as they

are many. Comments are encouraged. If there is something that doesn't look right, please provide input on how to fix it. Target draft completion by next week's call (include transmitter and receiver sections.

5. Schedule

Face-to-face August 15 and 16 in Lisle, IL http://www.t10.org/ftp/t10/t10r/2007/r0707166.htm

Next call: August 9, 2007 10:00 am CDT

Toll Free Dial in Number: (877)810-9442 International Access/Caller Paid Dial In Number: (636)651-3190 PARTICIPANT CODE: 3243413

Webex information: <u>https://seagate.webex.com/seagate</u> Topic: SAS-2 PHY WG Date: Thursday Time: 10:00 am, Central Daylight Time (GMT -05:00, Chicago) Meeting number: 826 515 680 Meeting password: 6gbpsSAS